

# 3-STATE Octal D-Type Latch MM74HC373

### **General Description**

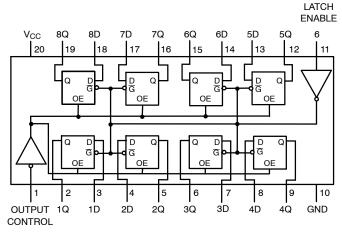
The MM74HC373 high speed octal D-type latches utilize advanced silicon-gate CMOS technology. They possess the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads. Due to the large output drive capability and the 3-STATE feature, these devices are ideally suited for interfacing with bus lines in a bus organized system.

When the LATCH ENABLE input is HIGH, the Q outputs will follow the D inputs. When the LATCH ENABLE goes LOW, data at the D inputs will be retained at the outputs until LATCH ENABLE returns HIGH again. When a high logic level is applied to the OUTPUT CONTROL input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

The 74HC logic family is speed, function, and pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{\rm CC}$  and ground.

#### **Features**

- Typical Propagation Delay: 18 ns
- Wide Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA Maximum
- Low Quiescent Current: 160 μA Maximum (74 Series)
- Output Drive Capability: 15 LS-TTL Loads
- This is a Pb-Free Device



Pin Assignments for SOIC and TSSOP (Top View)

Figure 1. Connection Diagram

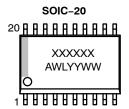
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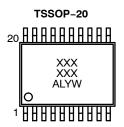






#### **MARKING DIAGRAMS**





XXXXXX = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot Number
Y = Year
WW, YW = Work Week

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 5 of this data sheet.

# TRUTH TABLE

Output Control	Latch Enable	Data	373 Output
L	Н	Н	Н
L	Н	L	L
L	L	Х	$Q_0$
Н	Х	X	Z

#### NOTES:

H = HIGH Level

L = LOW Level

X = Don't Care

 $Q_0$  = Level of output before steady-state input conditions were

established.

Z = High Impedance

# ABSOLUTE MAXIMUM RATINGS (Note 1)

Symbol	Rating		Value	Unit
V <sub>CC</sub>	Supply Voltage		−0.5 to +6.5 V	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to V <sub>CC</sub> +0.5 V	V
V <sub>OUT</sub>	DC Output Voltage		-0.5 to V <sub>CC</sub> +0.5 V	V
I <sub>IK</sub> , I <sub>OK</sub>	Clamp Diode Current		±20	mA
I <sub>OUT</sub>	DC Output Current, per pin		±35	mA
I <sub>CC</sub>	DC V <sub>CC</sub> or GND Current, per pin		±70	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
P <sub>D</sub>	Power Dissipation SOIC		1302	mW
		TSSOP	833	mW
T <sub>L</sub>	Lead Temperature (Soldering 10 seconds)		260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	Supply Voltage		2	6	٧
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input or Output Voltage		0	V <sub>CC</sub>	٧
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise or Fall Times	V <sub>CC</sub> = 2.0 V	-	1000	ns
		V <sub>CC</sub> = 4.5 V	-	500	ns
		V <sub>CC</sub> = 6.0 V	-	400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

<sup>1.</sup> Unless otherwise specified all voltages are referenced to ground.

## DC ELECTRICAL CHARACTERISTICS (Note 2)

				T <sub>A</sub> =	25°C	T <sub>A</sub> = −40 to 85°C	T <sub>A</sub> = -55 to 125°C	
Symbol	Parameter	Conditions	V <sub>CC</sub>	Тур		Guaranteed L	imits	Unit
V <sub>IH</sub>	Minimum HIGH Level Input Voltage		2.0 V 4.5 V 6.0 V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V V V
V <sub>IL</sub>	Maximum LOW Level Input Voltage		2.0 V 4.5 V 6.0 V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V V
V <sub>OH</sub>	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \mu A$	2.0 V 4.5 V 6.0 V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 6.0 \text{ mA}$ $ I_{OUT}  \le 7.8 \text{ mA}$	4.5 V 6.0 V	4.2 5.7	3.98 5.48	3.84 5.34	3.7 5.2	V V
V <sub>OL</sub>	Maximum LOW Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \mu A$	2.0 V 4.5 V 6.0 V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 6.0 \text{ mA}$ $ I_{OUT}  \le 7.8 \text{ mA}$	4.5 V 6.0 V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V V
I <sub>IN</sub>	Maximum Input Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0 V		±0.1	±1.0	±1.0	μА
I <sub>OZ</sub>	Maximum 3-STATE Output Leakage Current	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $OC = V_{IH}$ $V_{OUT} = V_{CC} \text{ or GND}$	6.0 V		±0.5	±5	±10	μА
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0 V		8.0	80	160	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = 5 \text{ V}, T_A = 25^{\circ}C, t_r = t_f = 6 \text{ ns})$ 

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, Data to Q	C <sub>L</sub> = 45 pF	18	25	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, LE toQ	C <sub>L</sub> = 45 pF	21	30	ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Maximum Output Enable Time	$R_L = 1 \text{ k}\Omega,$ $C_L = 45 \text{ pF}$	20	28	ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Maximum Output Disable Time	$R_L = 1 \text{ k}\Omega,$ $C_L = 5 \text{ pF}$	18	25	ns
ts	Minimum Set Up Time			5	ns
t <sub>H</sub>	Minimum Hold Time			10	ns
t <sub>W</sub>	Minimum Pulse Width		9	16	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

For a power supply of 5 V ±10% the worst case output voltages (V<sub>OH</sub>, and V<sub>OL</sub>) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub> = 5.5 V and 4.5 V respectively. (The V<sub>IH</sub> value at 5.5 V is 3.85 V.) The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and I<sub>OZ</sub>) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

# **AC ELECTRICAL CHARACTERISTICS**

(V<sub>CC</sub> = 2.0–6.0 V,  $C_L$  = 50 pF,  $t_r$  =  $t_f$  = 6 ns, unless otherwise specified)

				T <sub>A</sub> =	25°C	T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	
Symbol	Parameter	Conditions	V <sub>cc</sub>	Тур		Guaranteed L	imits	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, Data to Q	C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	2.0 V 2.0 V	50 80	150 200	188 250	225 300	ns ns
		C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	4.5 V 4.5 V	22 30	30 40	37 50	45 60	ns ns
		C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	6.0 V 6.0 V	19 26	26 35	31 44	39 53	ns ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, LE to Q	C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	2.0 V 2.0 V	63 110	175 225	220 280	263 338	ns ns
		C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	4.5 V 4.5 V	25 35	35 45	44 56	52 68	ns ns
		C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	6.0 V 6.0 V	21 28	30 39	37 49	45 59	ns ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Maximum Output Enable Time	$R_L = 1 \text{ k}\Omega$ $C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	2.0 V 2.0 V	50 80	150 200	188 250	225 300	ns ns
		C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	4.5 V 4.5 V	21 30	30 40	37 50	45 60	ns ns
		C <sub>L</sub> = 50 pF C <sub>L</sub> = 150 pF	6.0 V 6.0 V	19 26	26 35	31 44	39 53	ns ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Maximum Output Disable Time	$R_L = 1 \text{ k}\Omega$ $C_L = 50 \text{ pF}$	2.0 V 4.5 V 6.0 V	50 21 19	150 30 26	188 37 31	225 45 39	ns ns ns
t <sub>s</sub>	Minimum Set Up Time		2.0 V 4.5 V 6.0 V	- - -	50 9 9	60 13 11	75 15 13	ns ns ns
t <sub>H</sub>	Minimum Hold Time		2.0 V 4.5 V 6.0 V	- - -	5 5 5	5 5 5	5 5 5	ns ns ns
t <sub>W</sub>	Minimum Pulse Width		2.0 V 4.5 V 6.0 V	30 10 9	80 16 14	100 20 18	120 24 20	ns ns ns
t <sub>THL</sub> , t <sub>TLH</sub>	Maximum Output Rise and Fall Time	C <sub>L</sub> = 50 pF	2.0 V 4.5 V 6.0 V	25 7 6	60 12 10	75 15 13	90 18 15	ns ns ns
C <sub>PD</sub>	Power Dissipation Capacitance (Note 3)	(per latch) OC = V <sub>CC</sub> OC = GND	- -	30 50	- -	- -	- -	pF pF
C <sub>IN</sub>	Maximum Input Capacitance		-	5	10	10	10	pF
C <sub>OUT</sub>	Maximum Output Capacitance		-	15	20	20	20	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. C<sub>PD</sub> determines the no load dynamic power consumption, P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup>f + I<sub>CC</sub> V<sub>CC</sub>, and the no load dynamic current consumption, I<sub>S</sub> = C<sub>PD</sub> V<sub>CC</sub> f + I<sub>CC</sub>.

# **ORDERING INFORMATION**

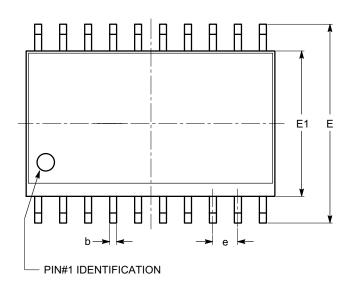
Device	Marking	Package	Shipping <sup>†</sup>
MM74HC373WM	HC373A	SOIC-20 WB (Pb-Free and Halide Free)	38 Units / Tube
MM74HC373WMX	HC373A	SOIC-20, 300 mils (Pb-Free and Halide Free)	1000 / Tape & Reel
MM74HC373MTC	HC 373A	TSSOP-20 WB (Pb-Free)	75 Units / Tube
MM74HC373MTCX	HC 373A	TSSOP-20 WB (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



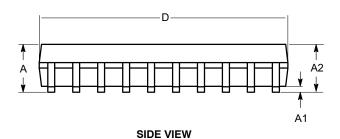
SOIC-20, 300 mils CASE 751BJ ISSUE O

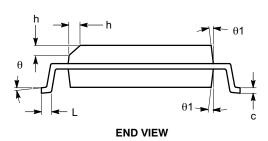
**DATE 19 DEC 2008** 



SYMBOL	MIN	NOM	MAX
Α	2.36	2.49	2.64
A1	0.10		0.30
A2	2.05		2.55
b	0.31	0.41	0.51
С	0.20	0.27	0.33
D	12.60	12.80	13.00
E	10.01	10.30	10.64
E1	7.40	7.50	7.60
е		1.27 BSC	
h	0.25		0.75
L	0.40	0.81	1.27
θ	0°		8°
θ1	5°		15°

**TOP VIEW** 





# Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-013.

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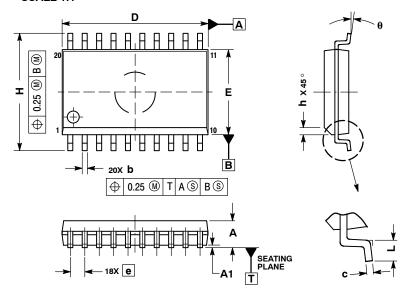




SOIC-20 WB CASE 751D-05 **ISSUE H** 

**DATE 22 APR 2015** 

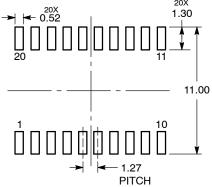
### SCALE 1:1



- DIMENSIONS ARE IN MILLIMETERS.
   INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

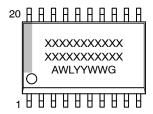
	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
b	0.35	0.49		
С	0.23	0.32		
D	12.65	12.95		
E	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
A	0 °	7 °		

### **RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

# **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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